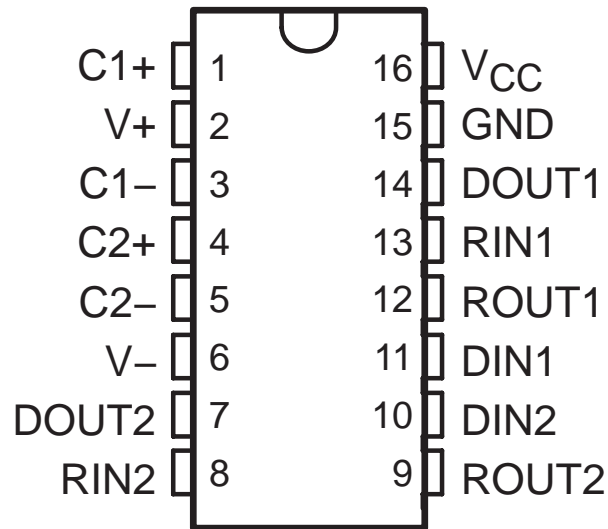


- RS-232 Bus-Pin ESD Protection Exceeds  $\pm 15$  kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V  $V_{CC}$  Supply
- Operates Up To 250 kbit/s
- Two Drivers and Two Receivers
- Low Supply Current . . . 300  $\mu$ A Typical
- External Capacitors . . .  $4 \times 0.1 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s)  
XD/XL3232
- Applications
  - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment



The XD/XL3232 device consists of two line drivers, two line receivers, and a dual charge-pump circuit with  $\pm 15$ -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The devices operate at data signaling rates up to 250 kbit/s and a maximum of 30-V/ $\mu$ s driver output slew rate.

**Function Tables**

**EACH DRIVER**

INPUT DIN	OUTPUT DOUT
L	H
H	L

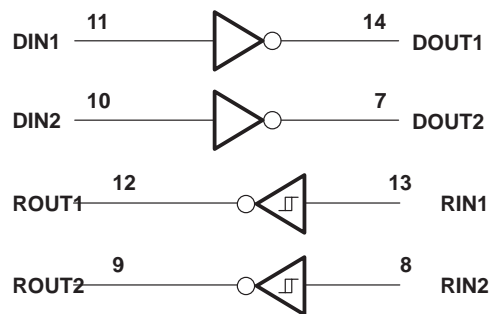
H = high level, L = low level

**EACH RECEIVER**

INPUT RIN	OUTPUT ROUT
L	H
H	L
Open	H

H = high level, L = low level, Open = input disconnected or connected driver off

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ (see Note 1)	-0.3 V to 6 V
Positive output supply voltage range, $V+$ (see Note 1)	-0.3 V to 7 V
Negative output supply voltage range, $V-$ (see Note 1)	0.3 V to -7 V
Supply voltage difference, $V+ - V-$ (see Note 1)	13 V
Input voltage range, $V_I$ : Drivers	-0.3 V to 6 V
Receivers	-25 V to 25 V
Output voltage range, $V_O$ : Drivers	-13.2 V to 13.2 V
Receivers	-0.3 V to $V_{CC} + 0.3 V$
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3): 3232	73 °C/W

Operating virtual junction temperature, $T_J$	150°C
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. Maximum power dissipation is a function of  $T_J(\max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

**recommended operating conditions (see Note 4 and Figure 4)**

		MIN	NOM	MAX	UNIT
Supply voltage	$V_{CC} = 3.3 V$	3	3.3	3.6	V
	$V_{CC} = 5 V$	4.5	5	5.5	
$V_{IH}$ Driver high-level input voltage	DIN	$V_{CC} = 3.3 V$	2		V
		$V_{CC} = 5 V$	2.4		
$V_{IL}$ Driver low-level input voltage	DIN			0.8	V
$V_I$	Driver input voltage	DIN	0	5.5	V
	Receiver input voltage		-25	25	
$T_A$ Operating free-air temperature	XD/XL3232			0	°C
				-40	

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu F$  at  $V_{CC} = 3.3 V \pm 0.3 V$ ; C1 = 0.047  $\mu F$ , C2–C4 = 0.33  $\mu F$  at  $V_{CC} = 5 V \pm 0.5 V$ .

**electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)**

PARAMETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
$I_{CC}$ Supply current	No load, $V_{CC} = 3.3 V$ or $5 V$		0.3	1	mA

‡ All typical values are at  $V_{CC} = 3.3 V$  or  $V_{CC} = 5 V$ , and  $T_A = 25^\circ C$ .

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu F$  at  $V_{CC} = 3.3 V \pm 0.3 V$ ; C1 = 0.047  $\mu F$ , C2–C4 = 0.33  $\mu F$  at  $V_{CC} = 5 V \pm 0.5 V$ .

**DRIVER SECTION**

**electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)**

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V <sub>OH</sub>	High-level output voltage	DOUT at R <sub>L</sub> = 3 kΩ to GND, DIN = GND	5	5.4		V
V <sub>OL</sub>	Low-level output voltage	DOUT at R <sub>L</sub> = 3 kΩ to GND, DIN = V <sub>CC</sub>	-5	-5.4		V
I <sub>IH</sub>	High-level input current	V <sub>I</sub> = V <sub>CC</sub>		±0.01	±1	μA
I <sub>IL</sub>	Low-level input current	V <sub>I</sub> at GND		±0.01	±1	μA
I <sub>OS</sub> ‡	Short-circuit output current	V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 0 V		±35	±60	mA
		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0 V				
r <sub>o</sub>	Output resistance	V <sub>CC</sub> , V+, and V- = 0 V, V <sub>O</sub> = ±2 V	300	10M		Ω

† All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

‡ Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.

**switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)**

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Maximum data rate		C <sub>L</sub> = 1000 pF, R <sub>L</sub> = 3 kΩ, One DOUT switching, See Figure 1	150	250		kbit/s
t <sub>sk(p)</sub>	Pulse skew§	C <sub>L</sub> = 150 pF to 2500 pF, R <sub>L</sub> = 3 kΩ to 7 kΩ, See Figure 2		300		ns
SR(tr)	Slew rate, transition region (see Figure 1)	R <sub>L</sub> = 3 kΩ to 7 kΩ, V <sub>CC</sub> = 3.3 V	C <sub>L</sub> = 150 pF to 1000 pF	6	30	V/μs
			C <sub>L</sub> = 150 pF to 2500 pF	4	30	

† All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

§ Pulse skew is defined as |t<sub>PLH</sub> - t<sub>PHL</sub>| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.

**RECEIVER SECTION**

**electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)**

PARAMETER	TEST CONDITIONS	MIN	TYPT <sup>†</sup>	MAX	UNIT
V <sub>OH</sub> High-level output voltage	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> -0.6V	V <sub>CC</sub> -0.1V		V
V <sub>OL</sub> Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V
V <sub>IT+</sub> Positive-going input threshold voltage	V <sub>CC</sub> = 3.3 V		1.5	2.4	V
	V <sub>CC</sub> = 5 V		1.8	2.4	
V <sub>IT-</sub> Negative-going input threshold voltage	V <sub>CC</sub> = 3.3 V	0.6	1.2		V
	V <sub>CC</sub> = 5 V	0.8	1.5		
V <sub>hys</sub> Input hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> )			0.3		V
r <sub>i</sub> Input resistance	V <sub>I</sub> = ±3 V to ±25 V	3	5	7	kΩ

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

NOTE 4: Test conditions are C1-C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2-C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.

**switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 3)**

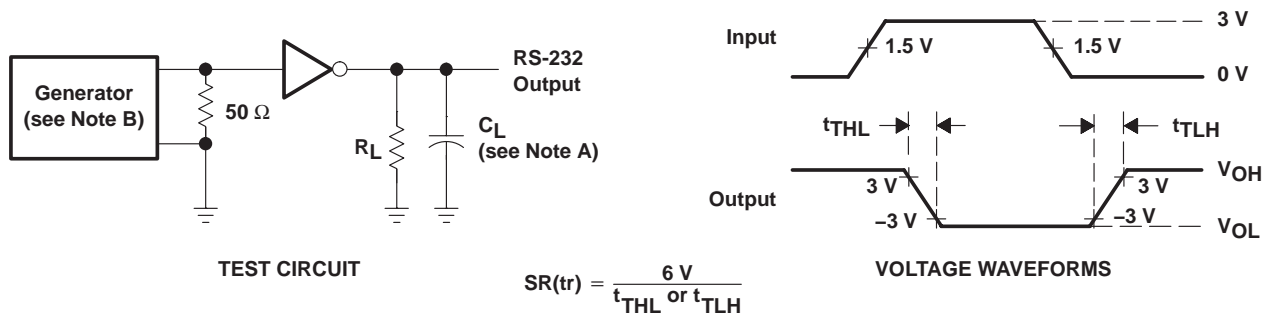
PARAMETER	TEST CONDITIONS	MIN	TYPT <sup>†</sup>	MAX	UNIT
t <sub>PLH</sub> Propagation delay time, low- to high-level output	C <sub>L</sub> = 150 pF		300		ns
t <sub>PHL</sub> Propagation delay time, high- to low-level output			300		ns
t <sub>sk(p)</sub> Pulse skew <sup>‡</sup>			300		ns

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

<sup>‡</sup> Pulse skew is defined as |t<sub>PLH</sub> - t<sub>PHL</sub>| of each channel of the same device.

NOTE 4: Test conditions are C1-C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2-C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.

**PARAMETER MEASUREMENT INFORMATION**

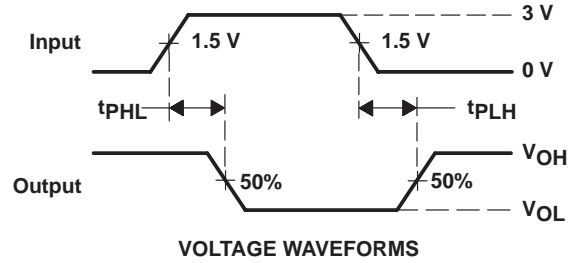
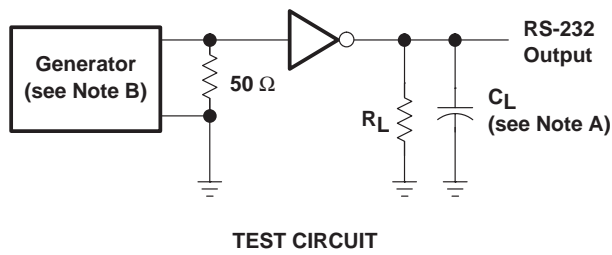


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z<sub>O</sub> = 50 Ω, 50% duty cycle, t<sub>r</sub> ≤ 10 ns, t<sub>f</sub> ≤ 10 ns.

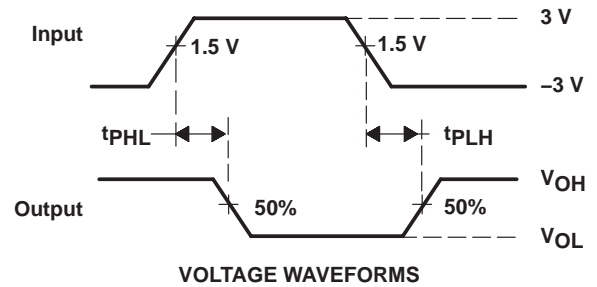
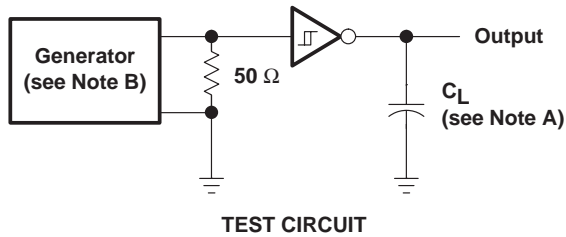
**Figure 1. Driver Slew Rate**

**PARAMETER MEASUREMENT INFORMATION**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

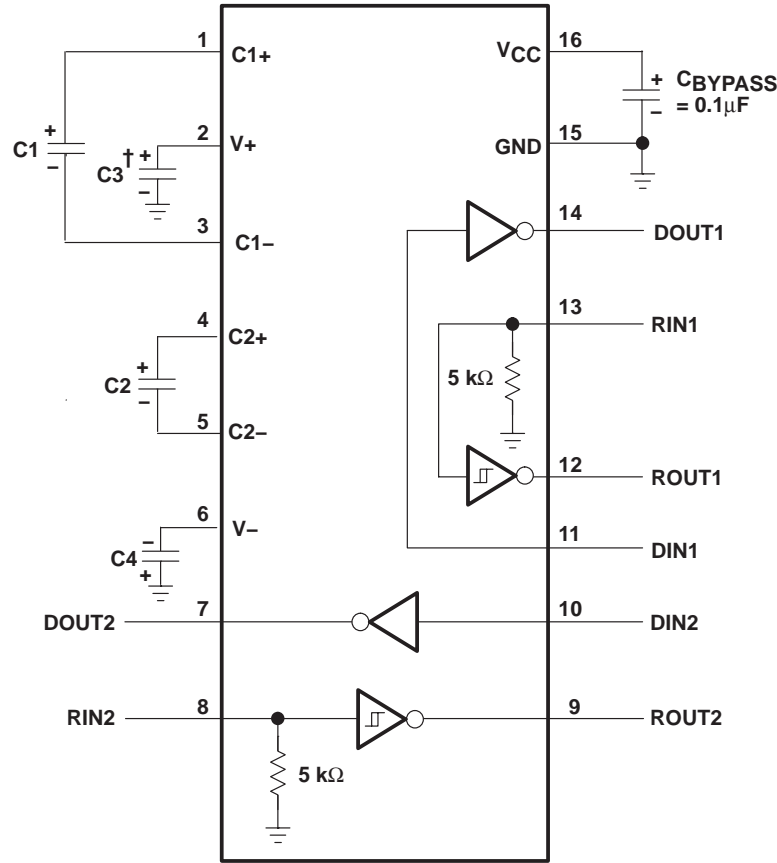
**Figure 2. Driver Pulse Skew**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

**Figure 3. Receiver Propagation Delay Times**

**APPLICATION INFORMATION**



† C3 can be connected to V<sub>CC</sub> or GND.

NOTES: A. Resistor values shown are nominal.

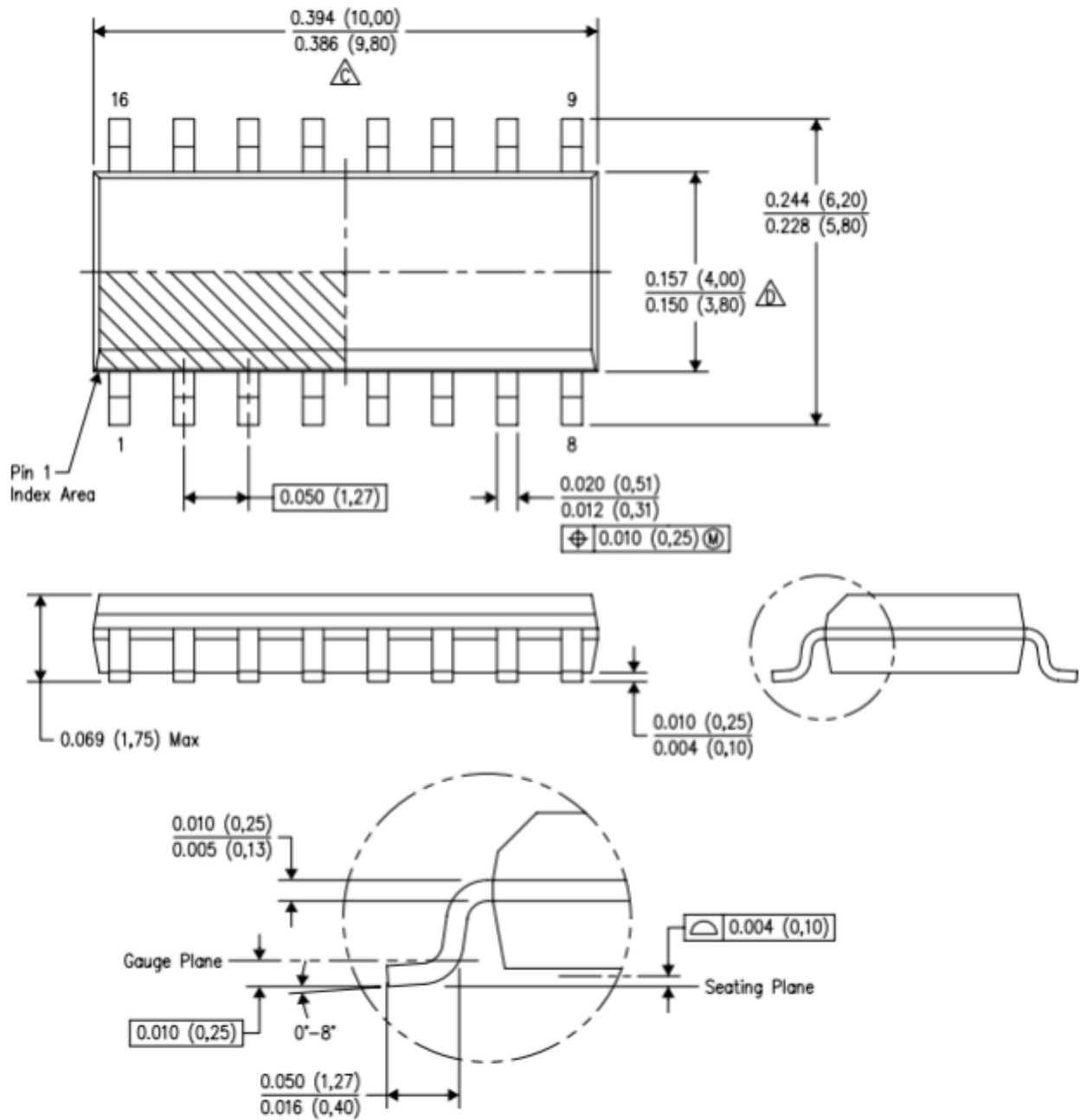
B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

**V<sub>CC</sub> vs CAPACITOR VALUES**

V <sub>CC</sub>	C1	C2, C3, C4
3.3 V ± 0.3 V	0.1 µF	0.1 µF
5 V ± 0.5 V	0.047 µF	0.33 µF
3 V to 5.5 V	0.1 µF	0.47 µF

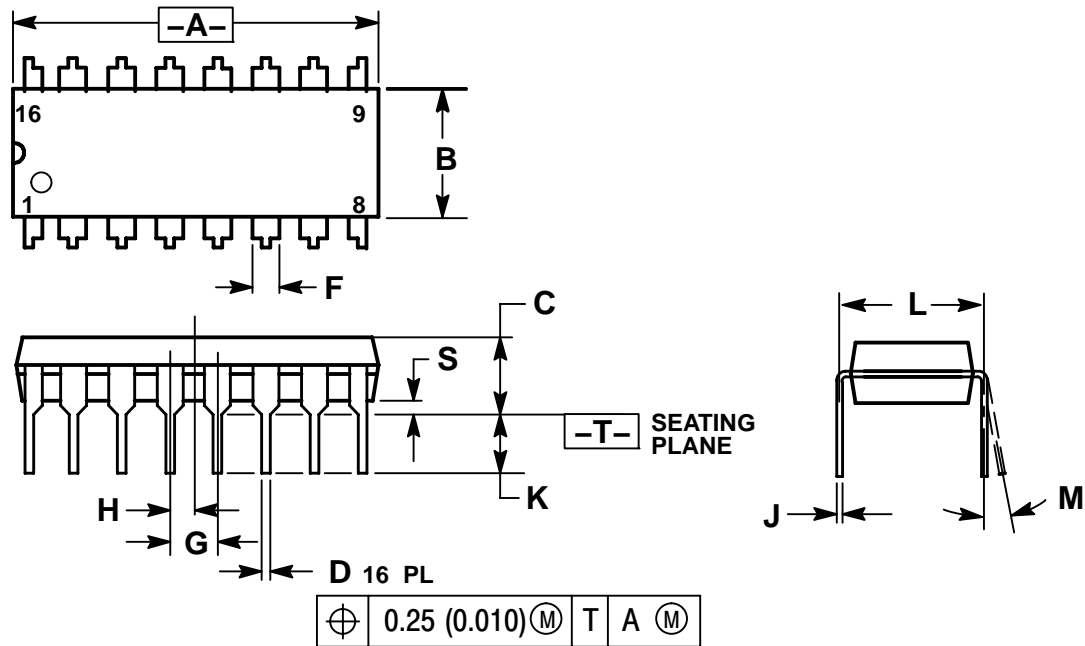
**Figure 4. Typical Operating Circuit and Capacitor Values**

SOP16





DIP16



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

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